



PROMEX INDUSTRIES INC., Mirror Semiconductor and Microbonds announce Alliance

(Santa Clara, Irvine, California & Toronto, Canada, (June 26, 2007) -- Promex Industries Inc., a privately held IC assembly and packaging foundry, Mirror Semiconductor, a privately held IC packaging start up and Microbonds Inc. a privately held Canadian corporation, are pleased to announce a co-development project to align existing capabilities, products and technology in order to generally qualify Microbonds X-Wire™ technology and to develop assembly & packaging processes to incorporate X-Wire into Mirror Semiconductor's "Mirrored Pinout" integrated circuits.

Promex Industries (www.promex-ind.com) is a leader in new product introduction (NPI), pre-Asia volume assembly and in preparing new technologies for transfer to high volume environments.

Both Mirror Semiconductor and Microbonds provide new packaging technologies designed to extend the life cycle and technical capabilities of today's packaging infrastructures with the least cost solution.

Mirror Semiconductor's Chip Packaging 2.0 Products and Services (www.mirrorsemi.com) allow package designers to create optimum circuit boards with shorter copper tracings and fewer layers at the lowest cost and reduced time to market.

Microbonds X-Wire Technology (www.microbonds.com) allows interconnect bonding wires to touch and cross without electrical shorting, permitting fuller utilization of the x,y and z dimensions in electronic packaging and design.

Today's IC designs and board designs are pushing the limits of current technologies as the industry continues to decrease geometries and costs while increasing functionality and interconnect densities. Providing package and board designers with the flexibility to solve these issues effectively, other than through the typical approach of increasing layers with their corresponding additional costs, necessitates collaborative development between adjacent processes and technologies.

This collaborative engineering effort will look to enable Promex to use X-Wire on behalf of its expanding customer base and co-develop package types utilizing Mirror Semiconductor's novel mirror pin out designs.

Richard Otte, CEO of Promex stated, " We are delighted to work with Microbonds and Mirror Semiconductor on this initiative. Our experience has taught us that the introduction of new materials and processes is much easier and faster when the parties can work openly together to achieve the goals of end customers. In particular we look forward to working with 20 micron X-Wire on a Mirrored Pin out package."

" Promex's proven ability to scale and transfer new technologies to volume production provides Mirror Semiconductor and our customers with the capabilities to take best advantage of our unique designs at the right combination of time and cost. X-Wire provides us with the flexibility to achieve complex package layouts with confidence", said Martin Hart, CEO of Mirror Semiconductor.

"This collaborative effort follows our approach of bringing X-Wire to market in a way that minimizes the time, cost and risk of adoption. We have been fortunate to build a number of technology and business alliances designed to provide wins for all involved, and this relationship provides companies interested in X-Wire with the ability to have packages built, tested and prepared for volume assembly with Promex or their packager of choice", added John Scott, CEO of Microbonds.

John Scott, CEO of Microbonds noted, "Mirror Semiconductor's innovative technology of Mirrored Pinout products demonstrates the capabilities of insulated bonding wire to enable reverse wire bonding with crossing wires to make the Mirrored Pinout packages without the risk of shorting. We are very pleased to have the opportunity to work with Mirror Semiconductor to advance their products and services".

Interested parties can see actual samples of Mirror Pin Out devices utilizing X-Wire at the upcoming Semicon West show in San Francisco July 16 to the 19th.

(<http://www.semiconwest.org/index.htm>). Completed Samples of Mirror packages with X-Wire will be on display at Tanaka, MKE and SPT booth locations.

About Promex

Promex (www.promex-ind.com) is a unique materials centric Packaging Foundry and IC Packaging assembly service provider. Molded plastic, ceramic and custom packaging solutions including SiPs, MEMS, MOEMS, MCMs, and LGA's are provided utilizing broad technical capabilities and RoHS expertise. Scalable capacity allows customer prototyping, "fast tracked" new product introductions and beta manufacturing through volume production.

About Mirror Semiconductor

Mirror Semiconductor is a start up company providing a host of solutions in the new Chip Packaging 2.0 environment. Mission is to provide board designers the ability to optimize their board designs with user definable pinout integrated circuit packaging. New IC packaging includes MirrorChip, AnyChip and StackChip packages. Our web site address is www.mirrorsemi.com

About Microbonds

Microbonds, Inc. is the leading developer and licensor of insulated wire bonding technologies for use in the design and assembly of microelectronic devices. Our web site address is www.microbonds.com

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